



DETAIL G
VIEW ROTATED 90° CW

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TITLE: THERMALLY ENHANCED QUAD FLAT NON-LEADED PACKAGE (QFN) 20 TERMINAL, 0.4 PITCH (3 X 3 X 0.6) EXPOSED LEAD END CASE OUTLINE	DOCUMENT NO: 98ARE10742D	REV: 0	
	CASE NUMBER: 2032-01	21 MAY 2008	
	STANDARD: NON-JEDEC		

NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.

2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M-1994.

3. COPLANARITY APPLIES TO LEADS, CORNER LEADS, AND DIE ATTACH PAD.

4. DIMENSION APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.20 MM AND 0.25 MM FROM TERMINAL TIP.

5. MIN. METAL GAP SHOULD BE 0.2MM.

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